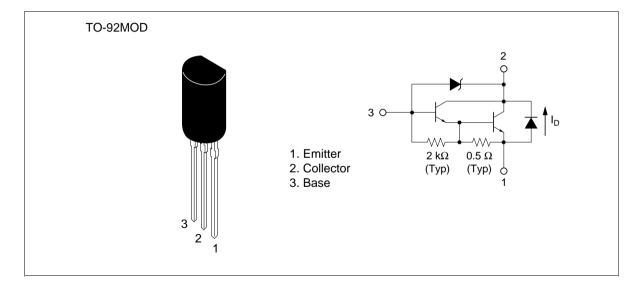
### Silicon NPN Epitaxial, Darlington

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#### Application

Low frequency power amplifier

#### Outline





#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

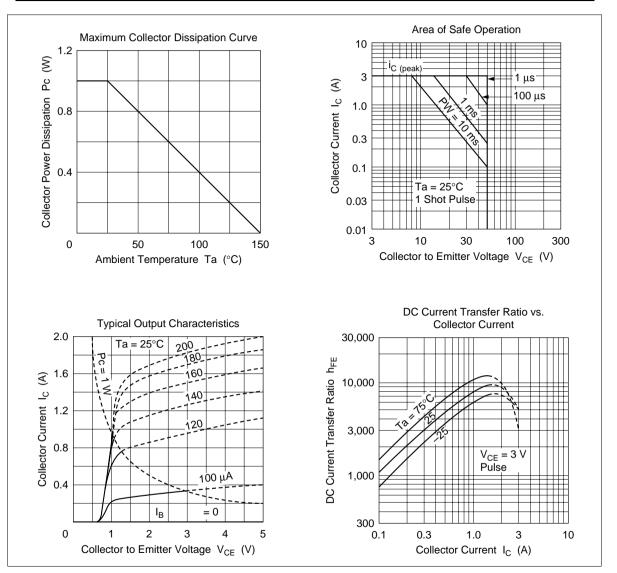
Item	Symbol	Ratings	Unit
Collector to base voltage	V <sub>CBO</sub>	50	V
Emitter to base voltage	V <sub>EBO</sub>	7	V
Collector current	Ι <sub>c</sub>	1.5	А
Collector peak current	ic (peak)	3.0	А
Collector power dissipation	Pc	1.0	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C
E to C diode forward current	Ι <sub>D</sub>	1.5	А

#### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

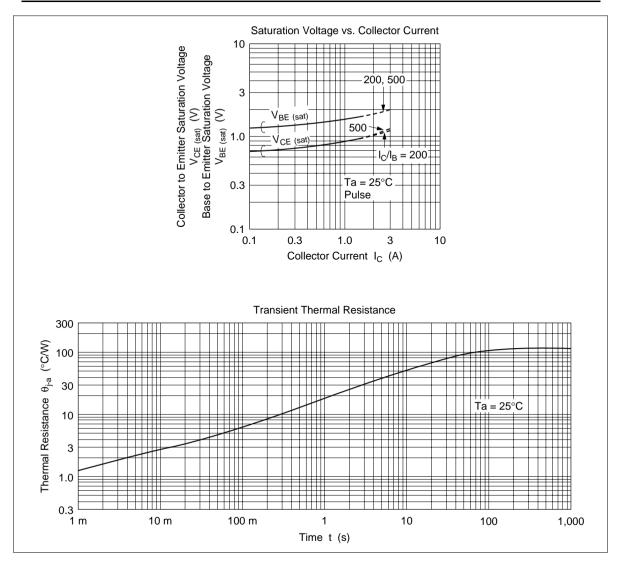
Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage (Zener breakdown voltage)	V <sub>(BR)CBO</sub> (V <sub>z</sub> )	50	60	70	V	$I_c = 0.1 \text{ mA}, I_e = \infty$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	50	_	_	V	$I_c$ = 10 mA, $R_{\scriptscriptstyle BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(\text{BR})\text{EBO}}$	7	_	_	V	$I_{\rm E} = 50$ mA, $I_{\rm C} = 0$
Collector cutoff current	I <sub>CEO</sub>	_		10	μA	$V_{CE}$ = 40 V, $R_{BE}$ = $\infty$
DC current transfer ratio	h <sub>FE</sub>	2000	_	10000		$V_{ce} = 3 V, I_c = 1 A^{*1}$
Collector to emitter saturation voltage	V <sub>CE(sat)1</sub>	—	_	1.5	V	$I_{c} = 1 \text{ A}, I_{B} = 1 \text{ mA}^{*1}$
	V <sub>CE(sat)2</sub>	_	_	2.0	V	$I_{c} = 1.5 \text{ A}, I_{B} = 1.5 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)1}$	—	_	2.0	V	$I_c = 1 \text{ A}, I_B = 1 \text{ mA}^{*1}$
	V <sub>BE(sat)2</sub>	—		2.5	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 1.5 \text{ mA}^{*1}$
E to C diode forward voltage	V <sub>D</sub>			3.0	V	$I_{\rm D} = 1.5 \ {\rm A}^{*1}$

Note: 1. Pulse test

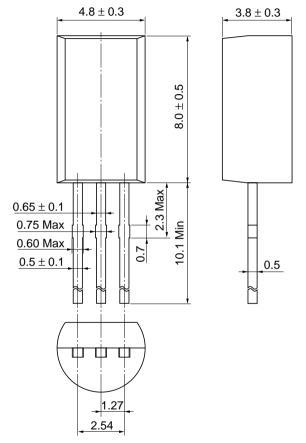
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#### Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

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